

**REMARKS**

Claims 9–20 are pending in the present application.

Claims 9 and 13–14 were amended herein.

Reconsideration of the claims is respectfully requested.

**35 U.S.C. § 102 (Anticipation)**

Claims 9–20 were rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,835,988 to *Ishii*. Claims 9, 17 and 20 were rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,744,863 to *Culnane et al.* These rejections are respectfully traversed.

A claim is anticipated only if each and every element is found, either expressly or inherently described, in a single prior art reference. The identical invention must be shown in as complete detail as is contained in the claim. MPEP § 2131 at p. 2100-73 (8<sup>th</sup> ed. rev. 2 May 2004).

Amended independent claim 9 recites that the lead frame includes one or more leads or pins and at least one other portion, and that part of the at least one other portion (i.e., a portion other than the pins or leads) is wrapped around the encapsulant. Similarly, independent claim 17 recites that the lead frame includes a die paddle, one or more leads or pins, and portions extending from the die paddle, and that the portions of the lead frame extending from the die paddle are folded around sides of the encapsulated integrated circuit die and over or adjacent to peripheral upper surfaces of the encapsulated integrated circuit die. In like manner independent claim 20 recites that the lead frame includes a die paddle on which an integrated circuit will be mounted, a plurality of structures which

will be formed into pins or leads for the integrated circuit package, and portions extending from the die paddle which will be folded around sides of the integrated circuit package and over or adjacent to a peripheral upper surface of the integrated circuit package to form an electrostatic discharge ring. Each of these claims thus makes clear that a portion of the lead frame separate from those portions that form leads or pins are wrapped around the encapsulant. Such a feature is not found in the cited references. *Ishii* teaches wrapping leads 4b around encapsulant 5b/5c. Similarly *Culhane et al* teaches wrapping leads 156 around ceramic chip carrier 152.

Amended independent claim 13 recites that the portion of the lead frame folded around encapsulant includes an opening therethrough to provide access for a connector to leads or pins connected to the integrated circuit. Such a feature is not found in the cited references. As noted above, both cited references teach wrapping only leads around the packaging structure. Such leads cannot logically – and do not – include openings therethrough to allow connection to those same leads.

Amended independent claim 14 recites that portions of the lead frame are folded only around edges of the encapsulated integrated circuit die not including leads or pins. Such a feature is not found in the cited references. The cited references teach only wrapping leads around the packaging structure, and not wrapping lead frame portions around other sides not including leads or pins.

Therefore, the rejection of claims 9–20 under 35 U.S.C. § 102 has been overcome.

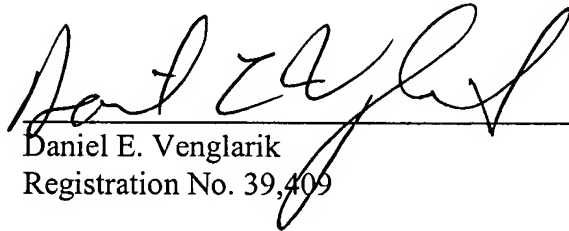
If any issues arise, or if the Examiner has any suggestions for expediting allowance of this Application, the Applicant respectfully invites the Examiner to contact the undersigned at the telephone number indicated below or at *dvenglarik@davismunck.com*.

The Commissioner is hereby authorized to charge any additional fees connected with this communication or credit any overpayment to Deposit Account No. 50-0208.

Respectfully submitted,

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